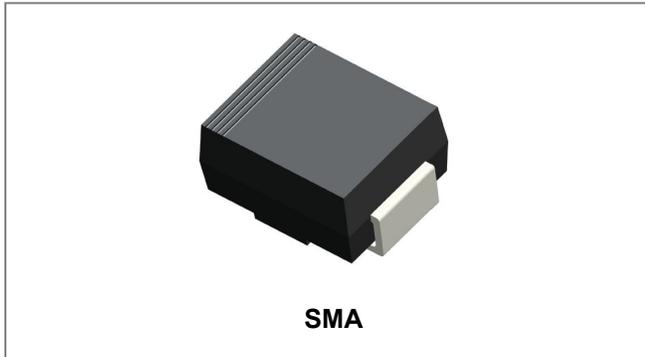


## GS2A THRU GS2M

### 2.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER



#### Features

- For surface mounted application
- Low forward voltage drop
- High current capability
- High reliability
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- This is a Pb – Free Device
- “-HF” suffix is for Halogen Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

#### Circuit Diagram



#### Mechanical Data

- Case: SMA molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.06 grams

#### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Characteristic	Symbol	GS2A	GS2B	GS2D	GS2G	GS2J	GS2K	GS2M	Units
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V <sub>R</sub>								
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @T <sub>L</sub> = 100°C	I <sub>o</sub>	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	60							A
Rating for fusing (t<8.3ms)	I <sup>2</sup> t	14.94							A <sup>2</sup> s
Forward Voltage @ I <sub>F</sub> = 2.0 A	V <sub>F</sub>	1.0							V
Peak Reverse Current @T <sub>A</sub> = 25°C	I <sub>RM</sub>	5.0							μA
At Rated DC Blocking Voltage @T <sub>A</sub> = 125°C		200							
Typical Junction Capacitance(Note1)	C <sub>J</sub>	12							pF
Typical Thermal Resistance Junction to Ambient (Note 2)	R <sub>θJA</sub>	50							°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175							°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. Thermal Resistance from Junction to Ambient at 0.375(9.5mm) lead length .

**Ratings and Characteristics Curves**

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

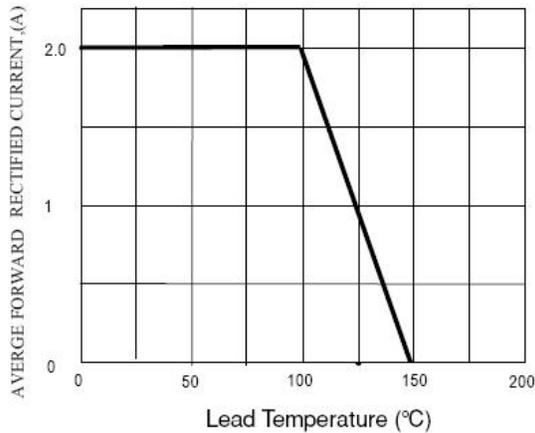


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

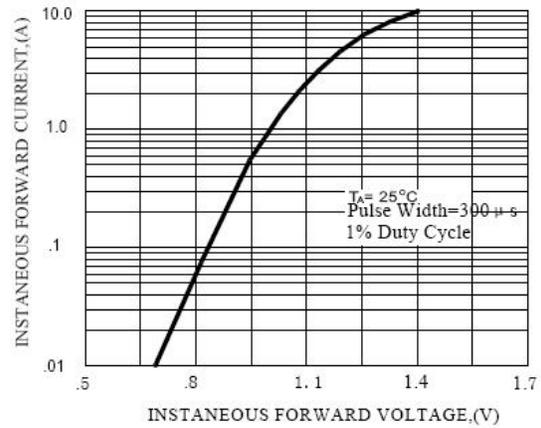


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

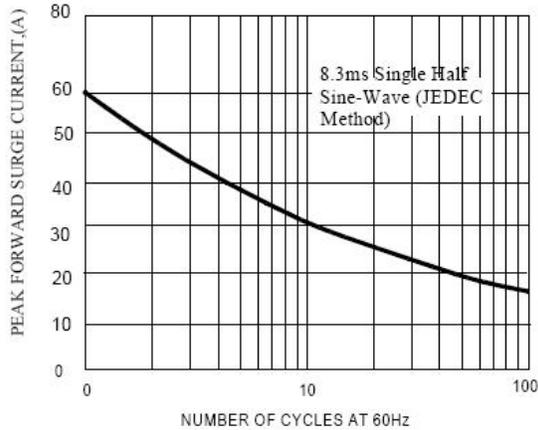
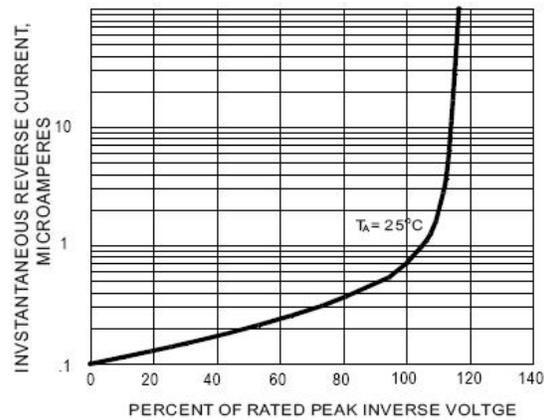
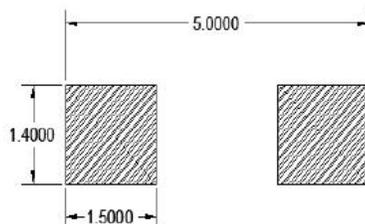
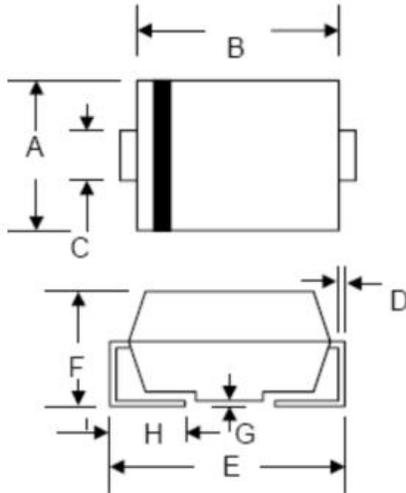


FIG.4-TYPICAL REVERSE CHARACTERISTICS



SMA PAD LAYOUT



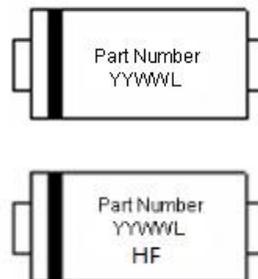
**Mechanical Dimensions SMA**


SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.40	2.84	0.094	0.112
B	3.99	4.75	0.157	0.187
C	1.05	1.70	0.041	0.067
D	0.15	0.51	0.006	0.020
E	4.80	5.66	0.189	0.223
F	1.90	2.95	0.075	0.116
G	0.05	0.25	0.002	0.010
H	0.76	1.52	0.030	0.600

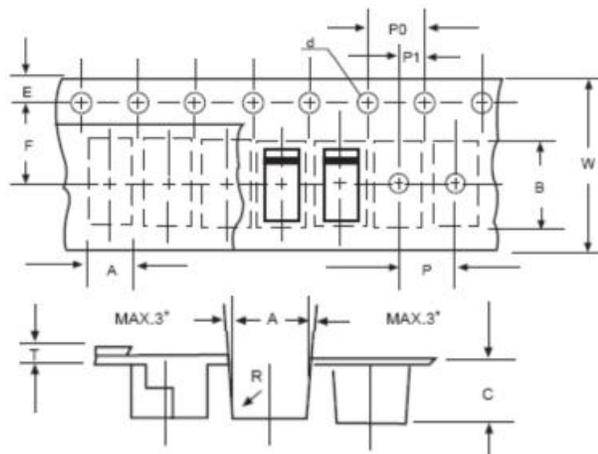
**Ordering Information**

Device	Package	Shipping
GS2A-GS2M	SMA	5000pcs / reel
GS2ATR-GS2MTR	SMA	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**


First row: Part Number (GS2A, GS2B, GS2D, GS2G, GS2J, GS2K, GS2M)  
 Second row: YYWWL  
 HF is Halogen Free  
 YY is the manufacture year,  
 WW is the manufacture week code,  
 L is the wafer's Lot Number

**Carrier Tape Specification SMA**


SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

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